TI Accelerates Femtocell Deployments with DSP Solution

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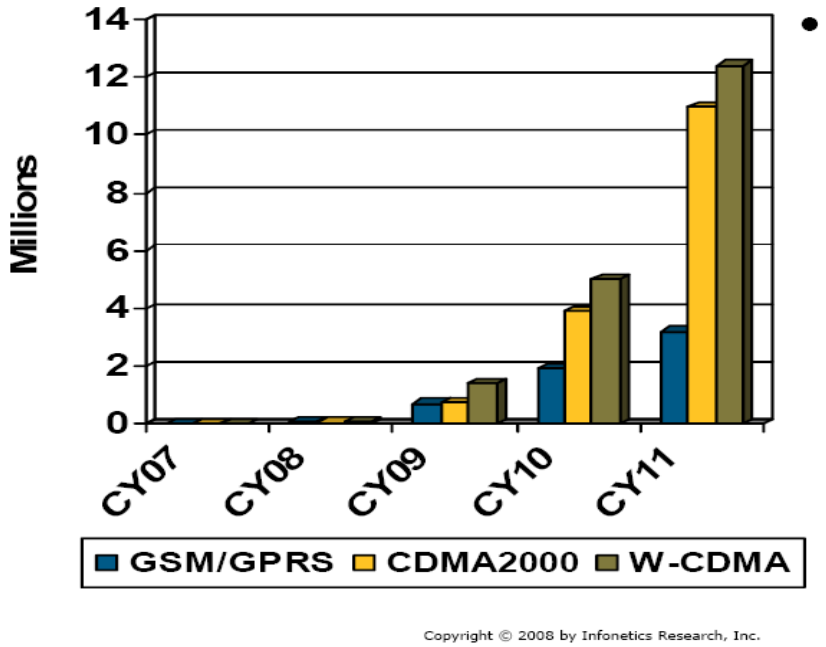
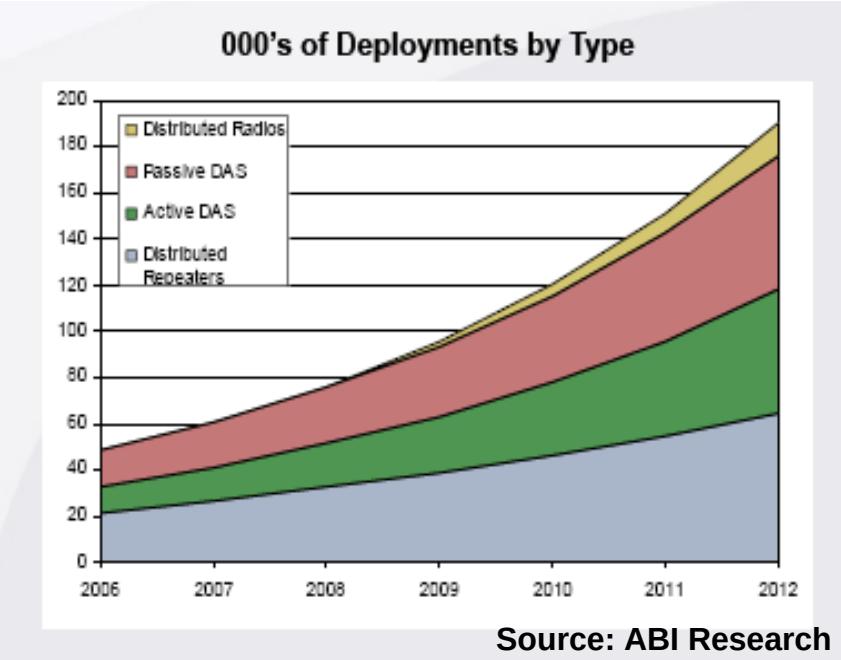
Femtocell Market: Early Trials, New Entrants Reflect Cautious Optimism

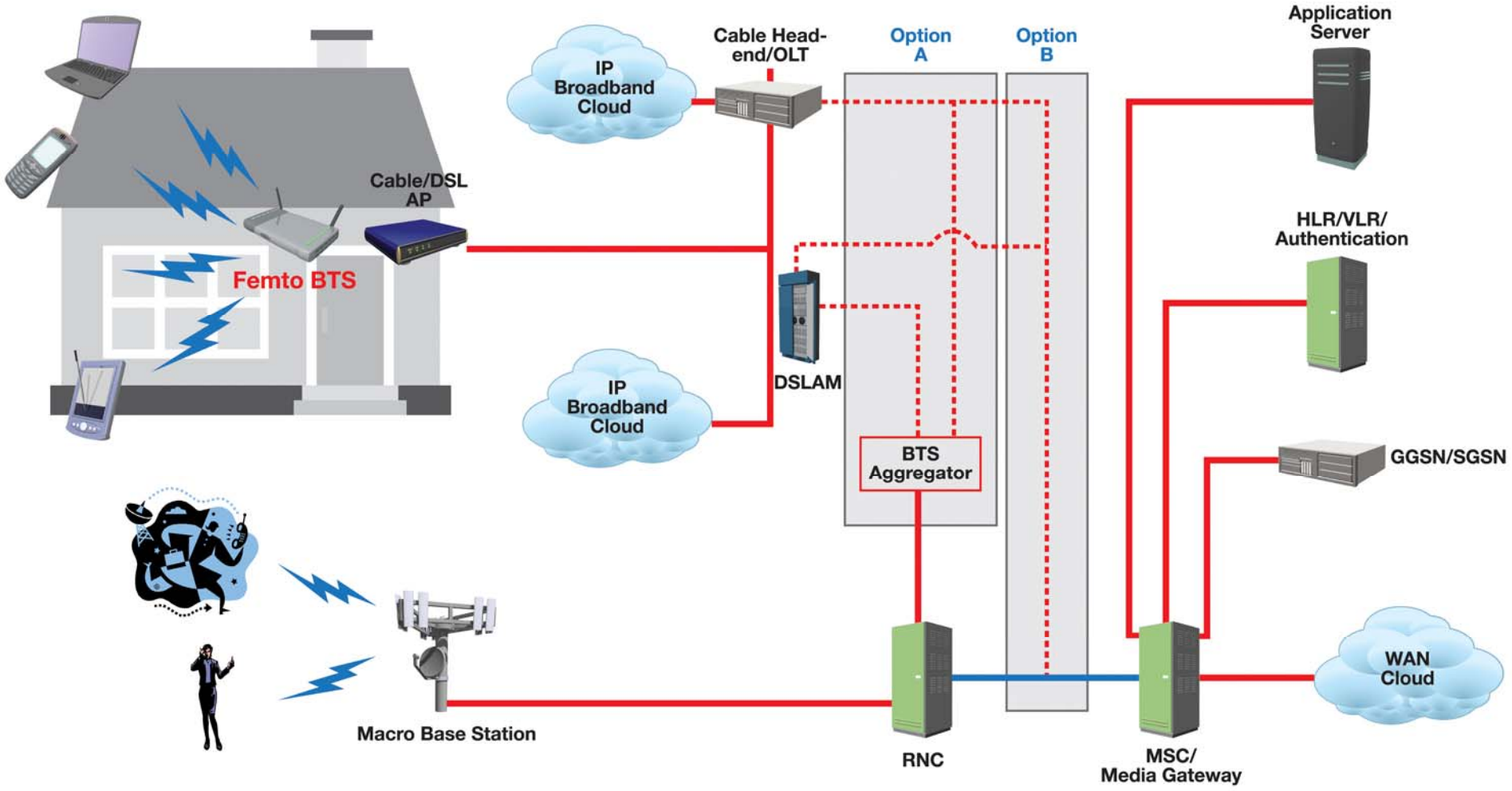




Source: ABI Research

- Trials show carrier consideration in US, Europe and Japan.
- New entrants/interest from cable and networking OEMs for both home and enterprise femtocell reflects broadening market.
- Support for all wireless standards reflects global opportunity.
- The big question now: Will the market take off?

Femto Network Architecture: Improving Call Quality and Increasing ARPU Options

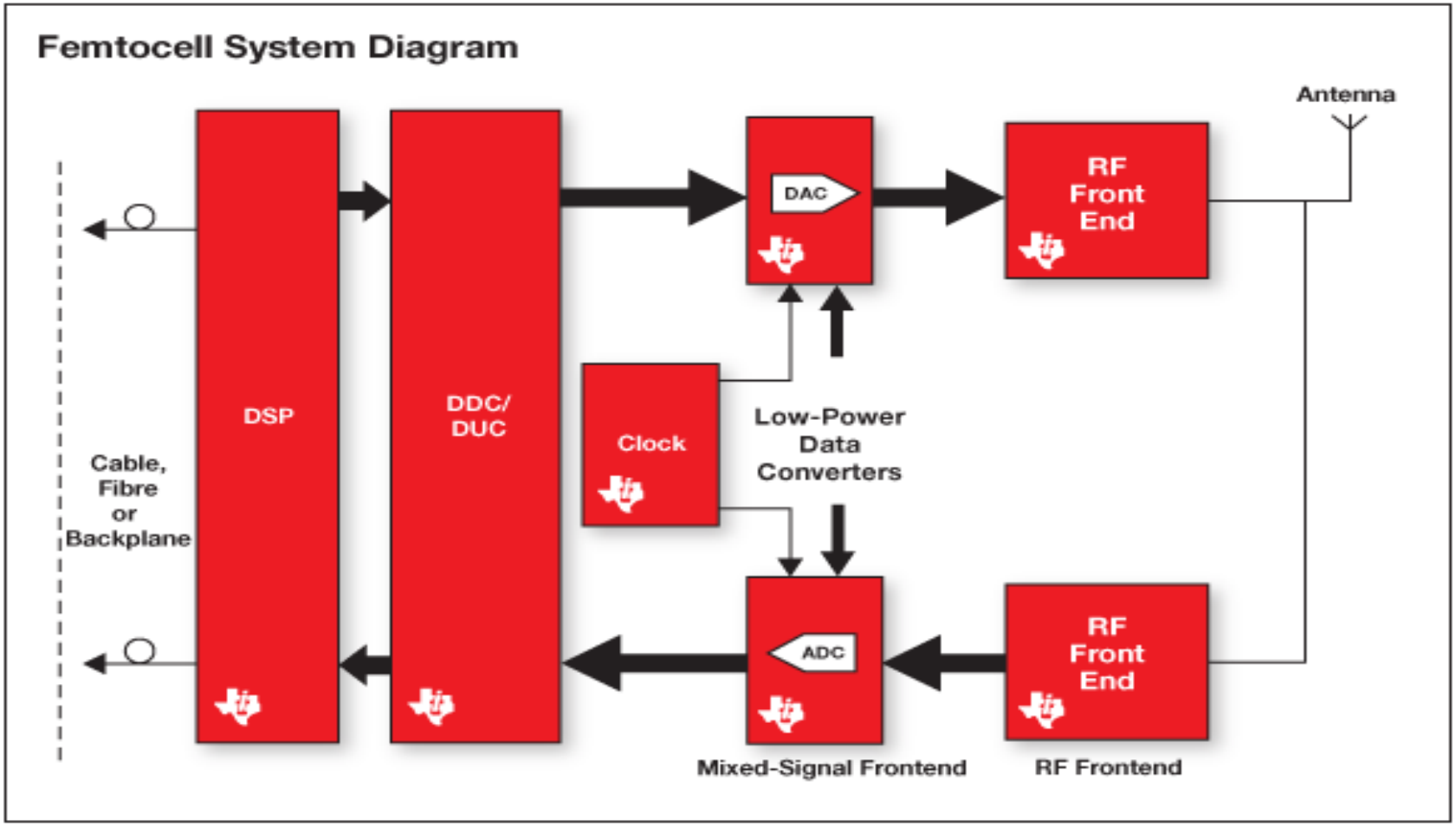


Option A: DSL & Cable Head End connected to Radio Network Controller via BTS gateway

Option B: DSL & Cable Head End connected directly to MSC/Media Gateway

TI Technology Enables Successful Femtocell Model

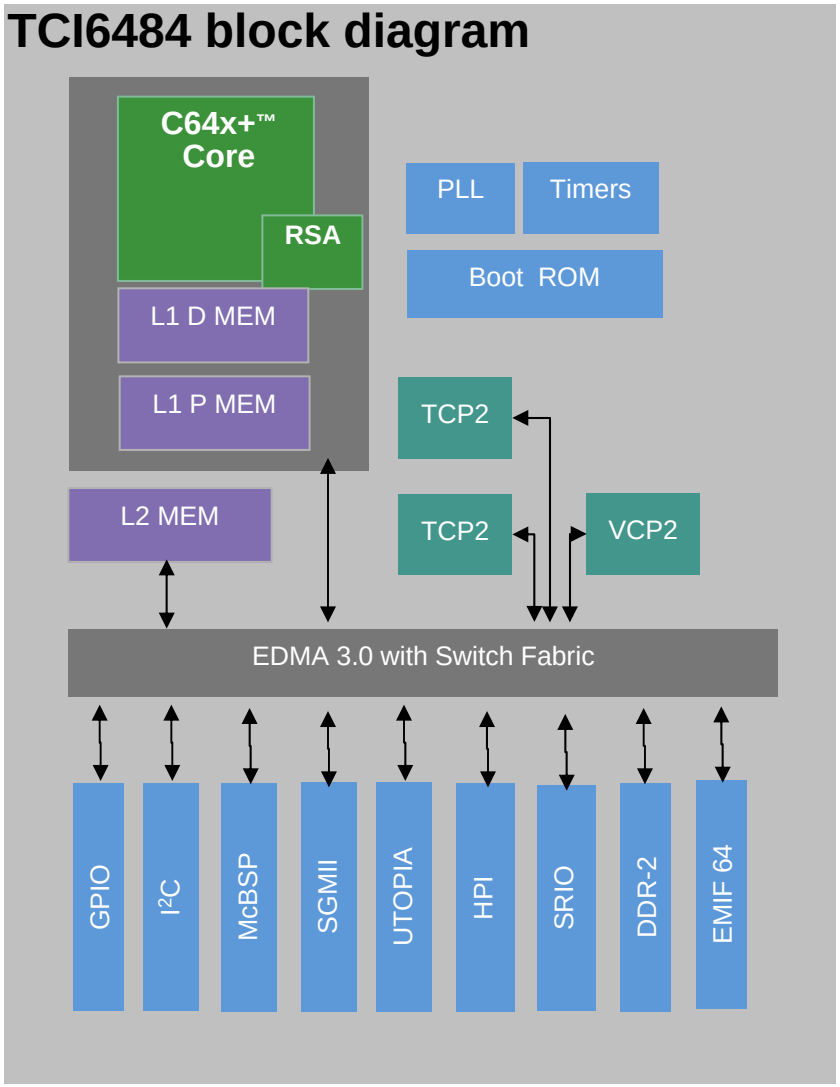
Solution Components Currently Deployed in 90% of the Global Basestations



TCI6484: High Performance + Small Size

Key Features:

- **50% cost/power/board savings** by eliminating the need for a RISC processor and PHY co-processor an integrating MAC and PHY functionality on a single device
- **Improved overall system functionality** with enhanced memory and cache performance for efficient MAC-layer processing:
  - -- Increased L2 cache size to 1 megagbyte (MB); total L2 memory of 2 MB
  - -- Increased 32-bit double data rate (DDR) memory speed to 667 MHz
- **Increased symbol rate processing** with up to 34 megabits per second (Mbps) of performance via dual Turbo Co-Processors (TCP2)
- **Support for multiple standards** with programmable platform: GSM-EDGE, EDGE Evolution, ,TD-SCDMA, WCDMA, HSPA, HSPA+, LTE, WiMAX
- **Scalable across multiple form-factors**: macro, micro, pico and femtocell base stations
- **Easy to use system design** with IO: sGMII for Ethernet, DDR2, EMIF for analog/rf interface



DSP+SW Solution Meets Diverse OEM/ Operator Needs

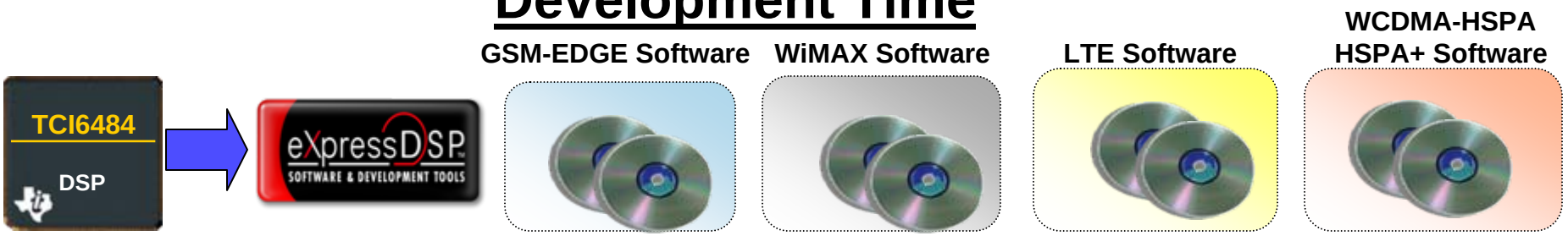
Customer Needs

- Basestation OEMs need **extensible platform** to enter market cost-effectively
- Cable OEMs need wireless infrastructure **system expertise** paired with cable modem platform
- Networking OEMs need **low power, flexibility** and support for **volume shipments**

Solution Benefits

- DSP-based solution is an extension of the same C6x+™ roadmap as **5-years of installed basestations**
- Programmable DSP allows OEMs to support **multiple standards** and unique operator configurations on a **single hardware platform**
- Highest performance/power ratio coupled with **field upgradeability** and a volume-based product

All Customers Benefit From Software – 50% in Development Time



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Questions?

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